



UNISONIC TECHNOLOGIES CO., LTD

## UTT68N03

POWER MOSFET

68A, 30V N-CHANNEL  
POWER MOSFET

### ■ DESCRIPTION

The UTC UTT68N03 is a N-channel mode power MOSFET using UTC's advanced technology to provide customers with a minimum on-state resistance, low gate charge and high switching speed.

The UTC UTT68N03 is suitable for high voltage synchronous rectifier and DC/DC converters, etc.

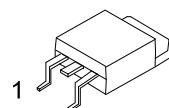
### ■ FEATURES

\*  $R_{DS(ON)} < 9.2 \text{ m}\Omega$  @  $V_{GS}=10\text{V}$ ,  $I_D=20\text{A}$

$R_{DS(ON)} < 18 \text{ m}\Omega$  @  $V_{GS}=4.5\text{V}$ ,  $I_D=20\text{A}$

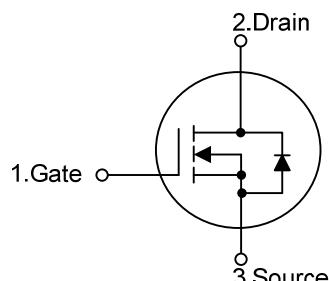
\* High Switching Speed

\* High Cell Density Trench Technology



TO-252

### ■ SYMBOL



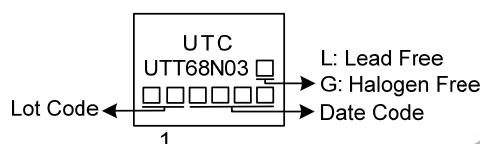
### ■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
UTT68N03L-TN3-R	UTT68N03G-TN3-R	TO-252	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

	(1)R: Tape Reel (2)TN3: TO-252 (3)G: Halogen Free and Lead Free, L: Lead Free
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### ■ MARKING



■ ABSOLUTE MAXIMUM RATING ( $T_c=25^\circ\text{C}$ , unless otherwise specified)

PARAMETER		SYMBOL	RATINGS		UNIT
Drain-Source Voltage		$V_{DSS}$	30		V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$		V
Drain Current	Continuous	$I_D$	68		A
	Pulsed (Note 2)	$I_{DM}$	136		A
Avalanche Energy (Note 3)	Single Pulsed (Note 3)	$E_{AS}$	21		mJ
Peak Diode Recovery $dv/dt$ (Note 4)		$dv/dt$	1.9		V/nS
Power Dissipation		$P_D$	50		W
Junction Temperature		$T_J$	+150		$^\circ\text{C}$
Storage Temperature Range		$T_{STG}$	-55 ~ +150		$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature

3.  $L=0.1\text{mH}$ ,  $I_{AS}=20.5\text{A}$ ,  $V_{DD}=50\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$

4.  $I_{SD} \leq 30\text{A}$ ,  $di/dt \leq 200\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_J \leq 25^\circ\text{C}$

## ■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS		UNIT
Junction to Ambient		$\theta_{JA}$	110		$^\circ\text{C}/\text{W}$
Junction to Case		$\theta_{JC}$	2.5 (Note)		$^\circ\text{C}/\text{W}$

Note: The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

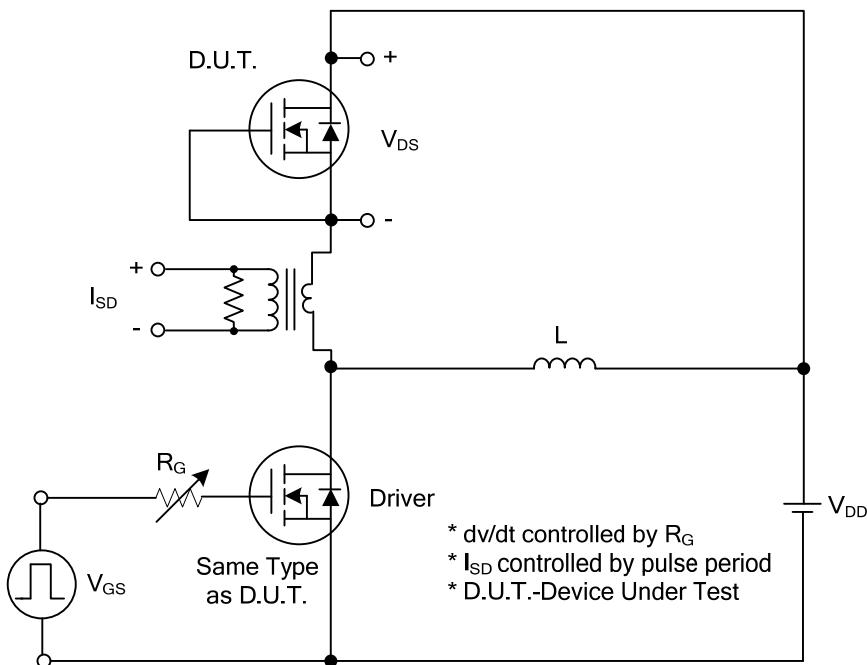
■ ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D=250\mu\text{A}$ , $V_{GS}=0\text{V}$	30			V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=68\text{V}$ , $V_{GS}=0\text{V}$		10		$\mu\text{A}$
Gate-Source Leakage Current	Forward	$I_{GSS}$	$V_{GS}=+20\text{V}$ , $V_{DS}=0\text{V}$		+100	nA
	Reverse		$V_{GS}=-20\text{V}$ , $V_{DS}=0\text{V}$		-100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	$V_{DS}=V_{GS}$ , $I_D=1\text{mA}$	0.8		2.0	V
Static Drain-Source On-State Resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}$ , $I_D=20\text{A}$			9.2	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=20\text{A}$			18	$\text{m}\Omega$
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	$C_{ISS}$	$V_{GS}=0\text{V}$ , $V_{DS}=25\text{V}$ , $f=1.0\text{MHz}$		1802		pF
Output Capacitance	$C_{OSS}$			275		pF
Reverse Transfer Capacitance	$C_{RSS}$			225		pF
<b>SWITCHING PARAMETERS</b>						
Total Gate Charge (Note 1)	$Q_G$	$V_{DS}=15\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=1.3\text{A}$ $I_G=1\text{mA}$ (Note 1, 2)		77		nC
Gate to Source Charge	$Q_{GS}$			7.6		nC
Gate to Drain Charge	$Q_{GD}$			12		nC
Turn-on Delay Time (Note 1)	$t_{D(\text{ON})}$	$V_{DS}=15\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=0.5\text{A}$ , $R_G=3\Omega$ (Note 1, 2)		24		ns
Rise Time	$t_R$			73		ns
Turn-off Delay Time	$t_{D(\text{OFF})}$			386		ns
Fall-Time	$t_F$			188		ns
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Maximum Body-Diode Continuous Current	$I_S$				68	A
Maximum Body-Diode Pulsed Current	$I_{SM}$				136	A
Drain-Source Diode Forward Voltage (Note 1)	$V_{SD}$	$I_S=68\text{A}$ , $V_{GS}=0\text{V}$			1.4	V
Reverse Recovery Time (Note 1)	$t_{rr}$	$I_S=68\text{A}$ , $V_{GS}=0\text{V}$ , $di/dt=30\text{A}/\mu\text{s}$		118		nS
Reverse Recovery Charge	$Q_{rr}$			191		nC

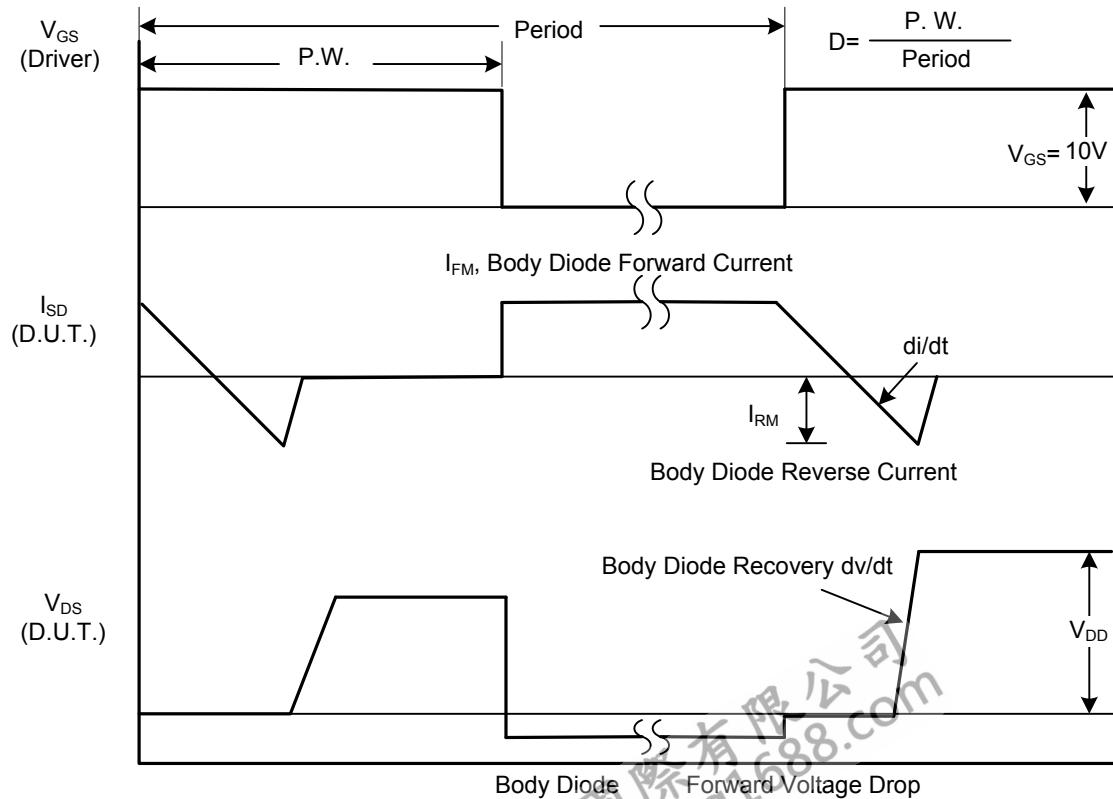
Notes: 1. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$ .

2. Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS

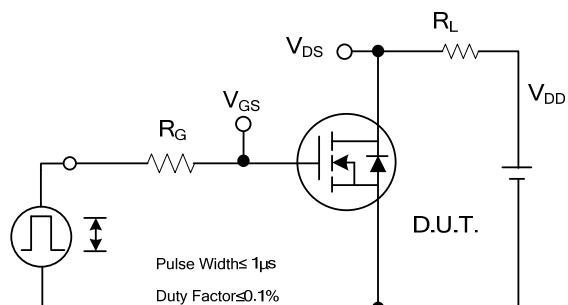


Peak Diode Recovery dv/dt Test Circuit

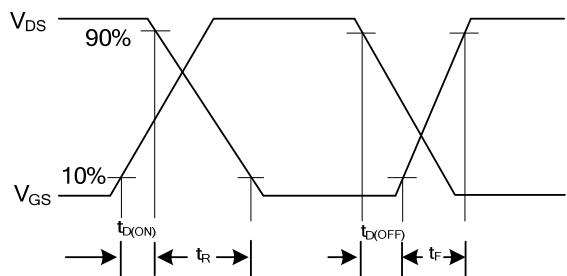


Peak Diode Recovery dv/dt Waveforms

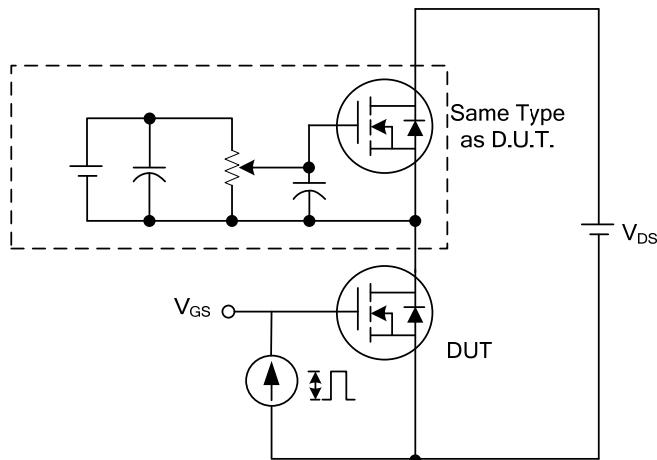
## ■ TEST CIRCUITS AND WAVEFORMS



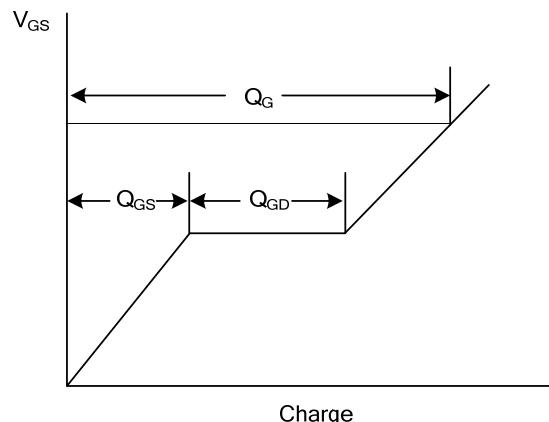
Switching Test Circuit



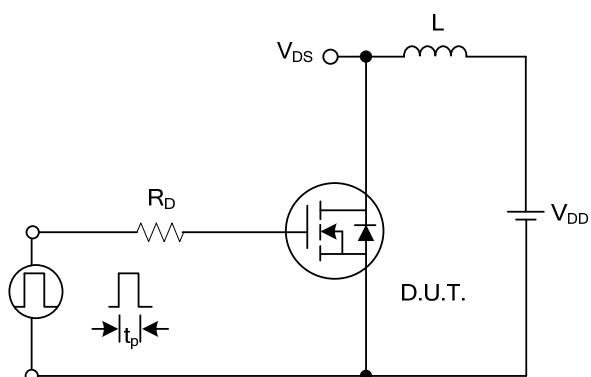
Switching Waveforms



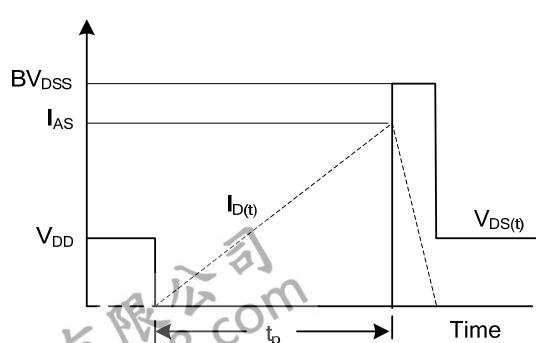
Gate Charge Test Circuit



Gate Charge Waveform

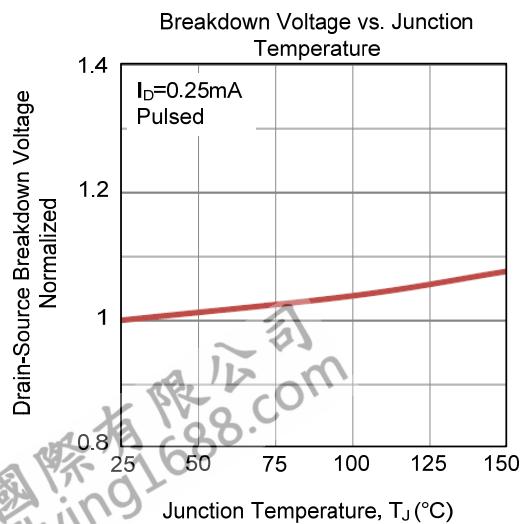
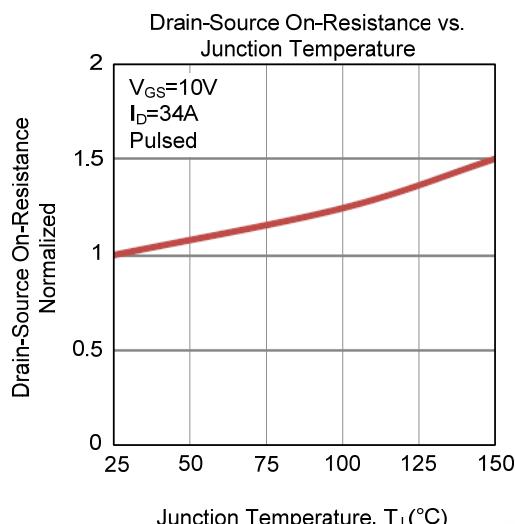
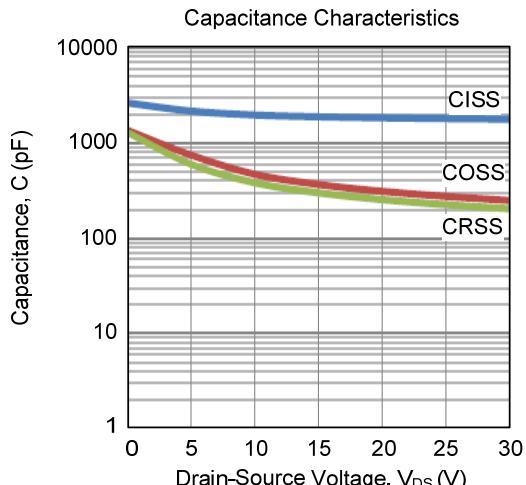
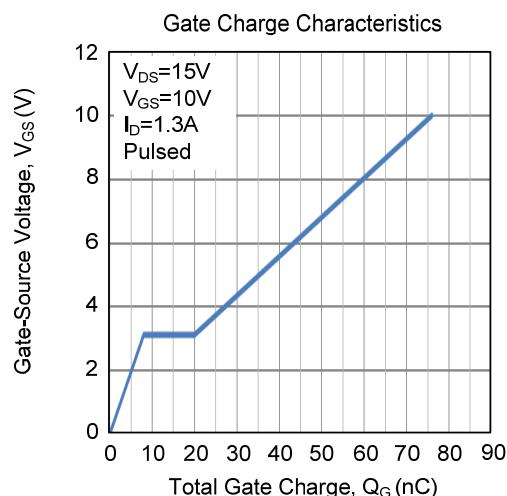
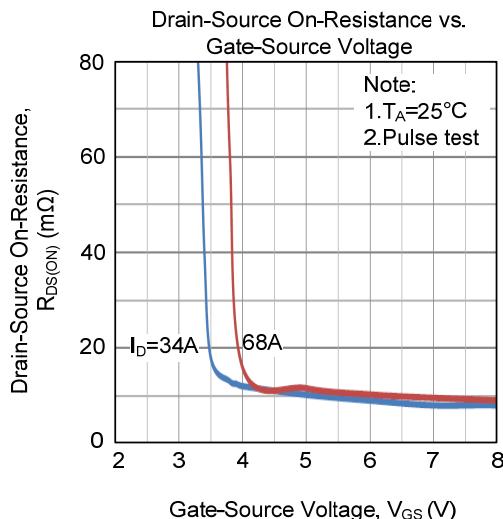
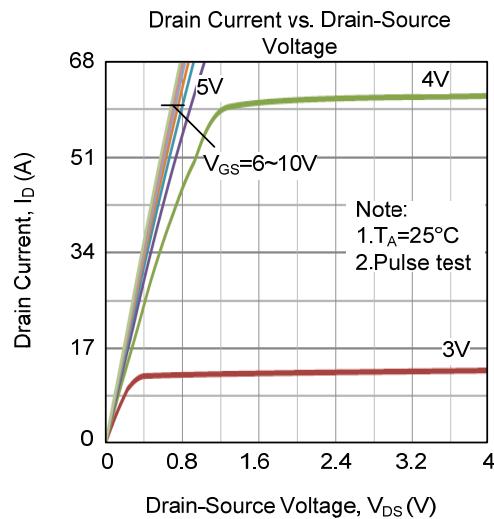


Unclamped Inductive Switching Test Circuit

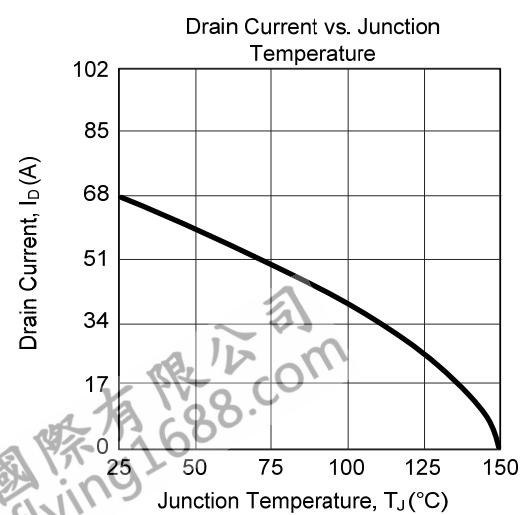
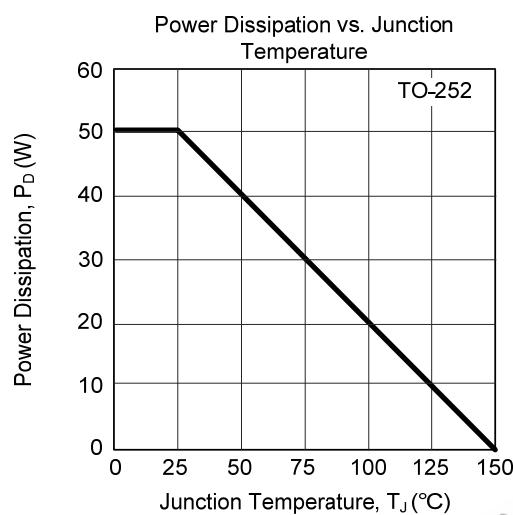
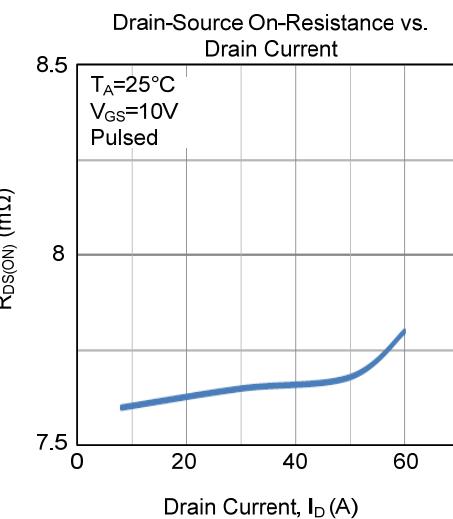
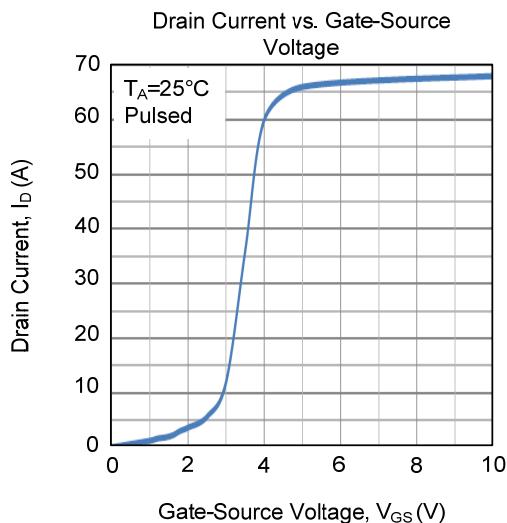
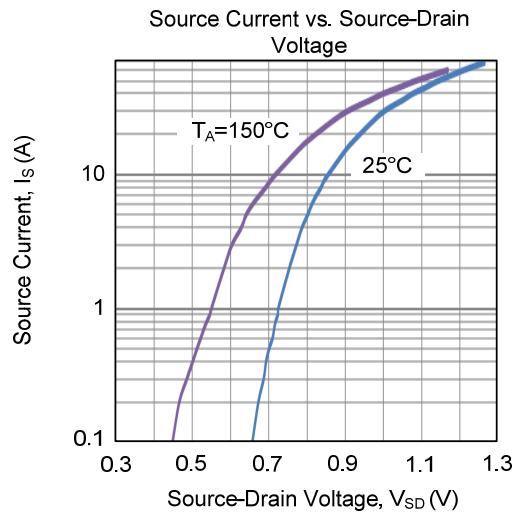
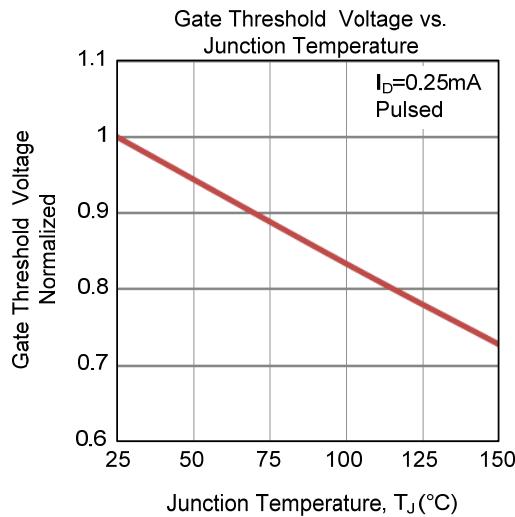


Unclamped Inductive Switching Waveforms

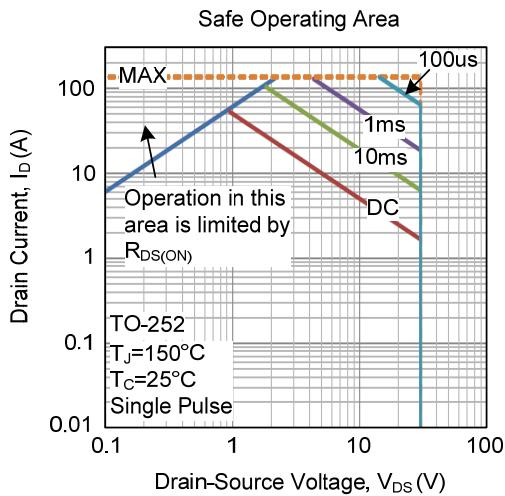
■ TYPICAL CHARACTERISTICS



## ■ TYPICAL CHARACTERISTICS (Cont.)



## ■ TYPICAL CHARACTERISTICS (Cont.)



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